

DGG, DGV, OR DL PACKAGE

### **FEATURES**

- Member of the Texas Instruments Widebus™ Family
- EPIC<sup>™</sup> (Enhanced-Performance Implanted CMOS) Submicron Process
- Checks Parity
- Able to Cascade With a Second SN74ALVCH16903
- ESD Protection Exceeds 2000 V Per MIL-STD-883, Method 3015; Exceeds 200 V Using Machine Model (C = 200 pF, R = 0)
- Latch-Up Performance Exceeds 250 mA Per JESD 17
- Bus Hold on Data Inputs Eliminates the Need for External Pullup/Pulldown Resistors
- Package Options Include Plastic 300-mil Shrink Small-Outline (DL), Thin Shrink Small-Outline (DGG), and Thin Very Small-Outline (DGV) Packages

### DESCRIPTION

This 12-bit universal bus driver is designed for 2.3-V to 3.6-V  $V_{\rm CC}$  operation.

The SN74ALVCH16903 has dual outputs and can operate as a buffer or an edge-triggered register. In both modes, parity is checked on APAR, which arrives one cycle after the data to which it applies. The YERR output, which is produced one cycle after APAR, is open drain.

MODE selects one of the two data paths. When MODE is low, the device operates as an edge-triggered register. On the positive transition of the clock (CLK) input and when the clock-enable

200,2	(TOP VI	IEW)
		<u> </u>
OE		56 CLK
1Y1	2	55 A
1Y2	3	54 311A/YERREN
GND	4	53 GND
2Y1	5	52 11Y1
2Y2 [	6	51 🛛 11Y2
v <sub>cc</sub> [	7	50 🛛 V <sub>CC</sub>
3Y1	8	49 🛛 2A
3Y2	9	48 🛛 3A
4Y1 [	10	47 🛛 4A
GND	11	46 🛛 GND
4Y2 [	12	45 🛛 12A
5Y1	13	44 🛛 12Y1
5Y2	14	43 <b>]</b> 12Y2
6Y1	15	42 <b>]</b> 5A
6Y2	16	41 🛛 6A
7Y1 [	17	40 <b>]</b> 7A
GND	18	39 🛛 GND
7Y2 [	19	38 🛛 APAR
8Y1 [	20	37 🛛 8A
8Y2 [	21	36 ] YERR
v <sub>cc</sub> [	22	35 ] V <sub>CC</sub>
9Y1 [	23	34 🛛 9A
9Y2	24	33 MODE
GND	25	32 🛛 GND
10Y1	26	31 ] 10A
10Y2	27	30 PARI/O
PAROE	28	29 CLKEN

(CLKEN) input is low, data set up at the A inputs is stored in the internal registers. On the positive transition of CLK and when CLKEN is high, only data set up at the 9A–12A inputs is stored in their internal registers. When MODE is high, the device operates as a buffer and data at the A inputs passes directly to the outputs. 11A/YERREN serves a dual purpose; it acts as a normal data bit and also enables YERR data to be clocked into the YERR output register.

When used as a single device, parity output enable (PAROE) must be tied high; when parity input/output (PARI/O) is low, even parity is selected and when PARI/O is high, odd parity is selected. When used in pairs and PAROE is low, the parity sum is output on PARI/O for cascading to the second SN74ALVCH16903. When used in pairs and PAROE is high, PARI/O accepts a partial parity sum from the first SN74ALVCH16903.

A buffered output-enable ( $\overline{OE}$ ) input can be used to place the 24 outputs and  $\overline{YERR}$  in either a normal logic state (high or low logic levels) or a high-impedance state. In the high-impedance state, the outputs neither load nor drive the bus lines significantly. The high-impedance state and increased drive provide the capability to drive bus lines without need for interface or pullup components.

OE does not affect the internal operation of the device. Old data can be retained or new data can be entered while the outputs are in the high-impedance state.



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# **DESCRIPTION (CONTINUED)**

To ensure the high-impedance state during power up or power down,  $\overline{OE}$  should be tied to V<sub>CC</sub> through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

IEXAS

Active bus-hold circuitry is provided to hold unused or floating data inputs at a valid logic level.

The SN74ALVCH16903 is characterized for operation from 0°C to 70°C.

### **FUNCTION TABLES**

#### FUNCTION

		INPUTS			OUTPUTS				
ŌĒ	MODE	CLKEN	CLK	Α	1Yn <sup>(1)</sup> –8Yn <sup>(1)</sup>	9Yn <sup>(1)</sup> –12Yn <sup>(1)</sup>			
L	L	L	$\uparrow$	Н	Н	Н			
L	L	L	$\uparrow$	L	L	L			
L	L	Н	$\uparrow$	Н	Y <sub>0</sub>	Н			
L	L	Н	$\uparrow$	L	Y <sub>0</sub>	L			
L	Н	Х	Х	Н	Н	Н			
L	Н	Х	Х	L	L	L			
н	Х	Х	Х	х	Z	Z			

(1) n = 1 or 2

### **PARITY FUNCTION**

		INF	UTS			OUTPUT
ŌĒ	PAROE <sup>(1)</sup>	11A/YERREN <sup>(2)</sup>	PARI/O	$\Sigma$ OF INPUTS 1A–10A = H	APAR	YERR
L	Н	L	L	0, 2, 4, 6, 8, 10	L	Н
L	Н	L	L	1, 3, 5, 7, 9	L	L
L	н	L	L	0, 2, 4, 6, 8, 10	Н	L
L	н	L	L	1, 3, 5, 7, 9	Н	Н
L	Н	L	Н	0, 2, 4, 6, 8, 10	L	L
L	н	L	Н	1, 3, 5, 7, 9	L	Н
L	н	L	Н	0, 2, 4, 6, 8, 10	Н	Н
L	Н	L	Н	1, 3, 5, 7, 9	Н	L
Н	Х	Х	Х	Х	Х	Н
L	Х	Н	Х	Х	Х	Н

(1) When used as a single device, PAROE must be tied high.

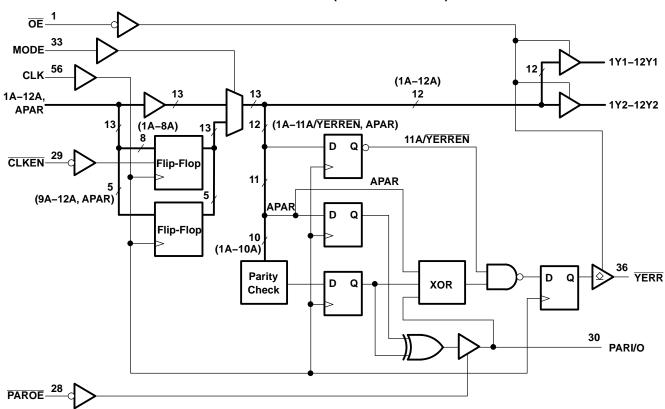
(2) Valid after appropriate number of clock pulses have set internal register

	INPUTS		OUTPUT
PAROE	$\Sigma$ OF INPUTS 1A–10A = H	APAR	PARI/O
L	0, 2, 4, 6, 8, 10	L	L
L	1, 3, 5, 7, 9	L	Н
L	0, 2, 4, 6, 8, 10	Н	Н
L	1, 3, 5, 7, 9	Н	L
Н	Х	Х	Z

#### PARI/O FUNCTION<sup>(1)</sup>

(1) This table applies to the first device of a cascaded pair of SN74ALVCH16903 devices.

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LOGIC DIAGRAM (POSITIVE LOGIC)

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ABSOLUTE MAXIMUM RATINGS<sup>(1)</sup>

over operating free-air temperature range (unless otherwise noted)

			MIN	MAX	UNIT
V <sub>CC</sub>	Supply voltage range		-0.5	4.6	V
VI	Input voltage range <sup>(2)</sup>		-0.5	4.6	V
Vo	Output voltage range <sup>(2)(3)</sup>		-0.5	V <sub>CC</sub> + 0.5	V
I <sub>IK</sub>	Input clamp current	V <sub>1</sub> < 0		-50	mA
I <sub>OK</sub>	Output clamp current	V <sub>O</sub> < 0		-50	mA
I <sub>O</sub>	Continuous output current			±50	mA
	Continuous current through each V <sub>CC</sub> or GN	ID		±100	mA
		DGG package		81	
$\theta_{JA}$	Package thermal impedance <sup>(4)</sup>	DGV package		86	°C/W
		DL package		74	
T <sub>stg</sub>	Storage temperature range		-65	150	°C

(1) Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

(2) The input negative-voltage and output voltage ratings may be exceeded if the input and output current ratings are observed.

(3) This value is limited to 4.6 V maximum.

(4) The package thermal impedance is calculated in accordance with JESD 51.

### **RECOMMENDED OPERATING CONDITIONS**<sup>(1)</sup>

				MIN	MAX	UNIT
V <sub>CC</sub>	Supply voltage			2.3	3.6	V
V	Llich lovel input veltage	$V_{CC}$ = 2.3 V to 2.7 V		1.7		V
V <sub>IH</sub>	High-level input voltage	$V_{CC}$ = 2.7 V to 3.6 V		2		v
V	Low lovel input veltage	$V_{CC}$ = 2.3 V to 2.7 V			0.7	V
V <sub>IL</sub>	Low-level input voltage	$V_{CC}$ = 2.7 V to 3.6 V			0.8	v
VI	Input voltage			0	V <sub>CC</sub>	V
Vo	Output voltage			0	V <sub>CC</sub>	V
	H High-level output current	$V_{CC} = 2.3 V$	Y port		-12	
		$V_{CC} = 2.7 V$	r poit		-12	mA
I <sub>OH</sub>		$V_{CC} = 3 V$	PARI/O		-12	ШA
		$v_{\rm CC} = 3 v$	Y port		-24	
		$V_{CC} = 2.3 V$	V port		12	
		$V_{CC} = 2.7 V$	Y port		12	
I <sub>OL</sub>	Low-level output current		PARI/O		12	mA
		$V_{CC} = 3 V$	Y port		24	
			YERR output		24	
$\Delta t/\Delta v$	Input transition rise or fall rate	)		0	10	ns/V
T <sub>A</sub>	Operating free-air temperatur	perating free-air temperature			70	°C

 All unused control inputs of the device must be held at V<sub>CC</sub> or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.



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### **ELECTRICAL CHARACTERISTICS**

over recommended operating free-air temperature range (unless otherwise noted)

	PARAMETER	TEST C	CONDITIONS	V <sub>cc</sub>	MIN	TYP <sup>(1)</sup>	MAX	UNIT
		I <sub>OH</sub> = -100 μA		2.3 V to 3.6 V	V <sub>CC</sub> - 0.2			
		I <sub>OH</sub> = -6 mA,	V <sub>IH</sub> = 1.7 V	2.3 V	2			
	M as a set		V <sub>IH</sub> = 1.7 V	2.3 V	1.7			
V <sub>OH</sub>	Y port	I <sub>OH</sub> = -12 mA	N 0.V	2.7 V	2.2			V
			V <sub>IH</sub> = 2 V	3 V	2.4			
		I <sub>OH</sub> = -24 mA,	V <sub>IH</sub> = 2 V	3 V	2			
	PARI/O	I <sub>OH</sub> = -12 mA,	V <sub>IH</sub> = 2 V	3 V	2			
		I <sub>OL</sub> = 100 μA		2.3 V to 3.6 V			0.2	
		I <sub>OL</sub> = 6 mA,	V <sub>IL</sub> = 0.7 V	2.3 V			0.4	
	Y port	1 10 1	V <sub>IL</sub> = 0.7 V	2.3 V			0.7	
V <sub>OL</sub>		I <sub>OL</sub> = 12 mA	V <sub>IL</sub> = 0.8 V	2.7 V			0.4	V
		I <sub>OL</sub> = 24 mA,	V <sub>IL</sub> = 0.8 V	3 V			0.55	
-	PARI/O	I <sub>OL</sub> = 12 mA,	V <sub>IL</sub> = 0.8 V	3 V			0.55	
	YERR output	I <sub>OL</sub> = 24 mA		3 V			0.5	
l <sub>l</sub>		$V_{I} = V_{CC}$ or GND		3.6 V			±5	μΑ
		V <sub>I</sub> = 0.7 V		2.3 V	45			
		V <sub>I</sub> = 1.7 V		2.3 V	-45			
I <sub>I(hold)</sub>		V <sub>1</sub> = 0.8 V		3 V	75			μA
		V <sub>1</sub> = 2 V		3 V	-75			
		$V_{I} = 0$ to 3.6 V <sup>(2)</sup>		3.6 V			±500	
l <sub>он</sub>	YERR output	$V_{O} = V_{CC}$		0 to 3.6 V			±10	μΑ
l <sub>oz</sub> <sup>(3)</sup>		$V_{O} = V_{CC}$ or GND		3.6 V			±10	μΑ
I <sub>CC</sub>		$V_{I} = V_{CC}$ or GND,	l <sub>O</sub> = 0	3.6 V			40	μΑ
ΔI <sub>CC</sub>		One input at V <sub>CC</sub> - 0.6 V,	Other inputs at $V_{CC}$ or GND	3 V to 3.6 V			750	μΑ
<u>^</u>	Control inputs			2.2.1/		5.5		- 5
Ci	Data inputs	$V_{I} = V_{CC}$ or GND		3.3 V		5.5		pF
<u>_</u>	YERR output			2.2.1/		5		~ Г
Co	Data outputs	$V_{O} = V_{CC}$ or GND		3.3 V		6		pF
C <sub>io</sub>	PARI/O	$V_0 = V_{CC}$ or GND		3.3 V		7		pF

(1)

All typical values are at  $V_{CC}$  = 3.3 V,  $T_A$  = 25°C. This is the bus-hold maximum dynamic current. It is the minimum overdrive current required to switch the input from one state to (2)

another.

For I/O ports, the parameter  $I_{OZ}$  includes the input leakage current. (3)



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### TIMING REQUIREMENTS

over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 1 and Figure 4)

				V <sub>CC</sub> = ± 0.2		V <sub>CC</sub> =	2.7 V	V <sub>CC</sub> = 3 ± 0.3	3.3 V 8 V	UNIT
				MIN	MAX	MIN	MAX	MIN	MAX	
f <sub>clock</sub>	Clock frequency				125		125		125	MHz
t <sub>w</sub>	Pulse duration, Cl	_K↑		3		3		3		ns
		1A–12A before CLK↑	Register mode	1.7		1.9		1.45		
		1A–10A before CLK↑	Buffer mode	5.9		5.2		4.4		
		up time APAR before CLK↑	Register mode	1.2		1.5		1.3		
t <sub>su</sub>	Setup time		Buffer mode	4.6		3.6		3.1		ns
		PARI/O before CLK↑	Both modes	2.4		2		1.7		
		11A/YERREN before CLK↑	Buffer mode	2		1.9		1.6		
		CLKEN before CLK↑	Register mode	2.5		2.6		2.2		
		1A–12A after CLK↑	Register mode	0.4		0.25		0.55		
		1A–10A after CLK↑	Buffer mode	0.25		0.25		0.25		
		APAR after CLK↑	Register mode	0.7		0.4		0.7		
	Hold time	APAR aller CLN	Buffer mode	0.25		0.25		0.25		~~~
t <sub>h</sub>		PARI/O after CLK1	Register mode	0.25		0.25		0.4		ns
		FARI/U aller ULKT	Buffer mode	0.25		0.25		0.5		
		11A/YERREN after CLK↑	Buffer mode	0.25		0.25		0.4		1
		CLKEN after CLK <sup>↑</sup>	Register mode	0.25		0.5		0.4		

### SWITCHING CHARACTERISTICS

over recommended operating free-air temperature range (unless otherwise noted) (see Figure 1 and Figure 4)

Р	ARAMETER	FROM (INPUT)	TO (OUTPUT)	V <sub>CC</sub> = ± 0.2		V <sub>CC</sub> =	2.7 V	V <sub>CC</sub> = 3.3 V ± 0.3 V		UNIT
		(INPOT)	(001201)	MIN	MAX	MIN	MAX	MIN	MAX	
f <sub>max</sub>				125		125		125		MHz
	Buffer mode	А	Y	1	4.4		4.2	1.1	3.8	
t <sub>pd</sub>	Deth medee		YERR	1	5.7		4.9	1.4	4.4	ns
	Both modes	CLK	PARI/O	1.2	8.6		7.9	1.7	6.6	
t <sub>pd</sub> <sup>(1)</sup>	Both modes	CLK	PARI/O	1	6.8		5.2	1.3	4.5	ns
t <sub>pd</sub>	Both modes	MODE	Y	1	5.9		5.8	1.3	4.9	ns
t <sub>PLH</sub>	De sister se de			1	6.1		5.5	1.2	4.8	
t <sub>PHL</sub>	Register mode	CLK	Y	1	5.9		4.9	1.2	4.6	ns
	Dette see de s	OE	Y	1.1	6.5		6.4	1.4	5.4	
t <sub>en</sub>	Both modes	PAROE	PARI/O	1	5.6		6	1	4.8	ns
		ŌE	Y	1	6.4		5.2	1.7	5	
t <sub>dis</sub>	lis Both modes	PAROE	PARI/O	1	3.2		3.8	1.2	3.8	ns
t <sub>PLH</sub>			VEDD	1	3.6		4.2	1.9	4	
t <sub>PHL</sub>	Both modes	ŌĒ	YERR	1.2	5.1		4.9	1.5	4.2	ns

(1) See Figure 2 and Figure 5 for the load specification.



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# SIMULTANEOUS SWITCHING CHARACTERISTICS<sup>(1)</sup>

(see Figure 3 and Figure 6)

PARAMETER		FROM (INPUT)	TO	$V_{CC}$ = 2.5 V ± 0.2 V		V <sub>CC</sub> = 2.7 V		V <sub>CC</sub> = 3.3 V ± 0.3 V		UNIT
		(INFUT)	(OUTPUT)	MIN	MAX	MIN	MAX	MIN	MAX	
t <sub>PLH</sub>	Degister mede		V	1.8	6.5		6.1	1.8	5	20
t <sub>PHL</sub>	Register mode	CLK	Ť	1.4	5.9		5.1	1.7	4.5	ns

(1) All outputs switching

### **OPERATING CHARACTERISTICS FOR BUFFER MODE**

 $T_A = 25^{\circ}C$ 

PARAMETER			TEST CONDITIONS				V <sub>CC</sub> = 3.3 V ± 0.3 V TYP	UNIT
~	Dower dissipation conscitance	Outputs enabled	<b>C</b> 0	f = 10 MHz	57.5	65	pF	
C <sub>pd</sub>	Power dissipation capacitance	Outputs disabled	C <sub>L</sub> = 0,		15	17.5	рг	

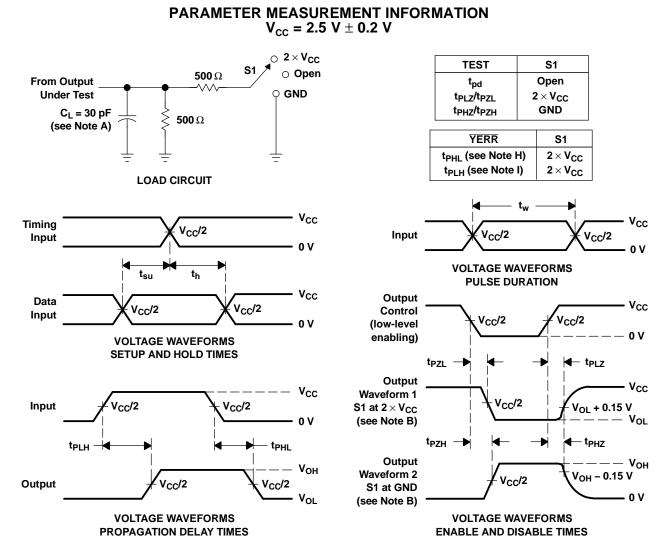
### **OPERATING CHARACTERISTICS FOR REGISTER MODE**

 $T_A = 25^{\circ}C$ 

	PARAMETER			ONDITIONS	V <sub>CC</sub> = 2.5 V ± 0.2 V TYP	V <sub>CC</sub> = 3.3 V ± 0.3 V TYP	UNIT	
<u>_</u>	Dower discinction experitence	Outputs enabled	<b>^ ^</b>	f 10 MU	57	87.5	ρF	
C <sub>pd</sub>	Power dissipation capacitance	Outputs disabled	C <sub>L</sub> = 0,	f = 10 MHz	16.5	34	рг	



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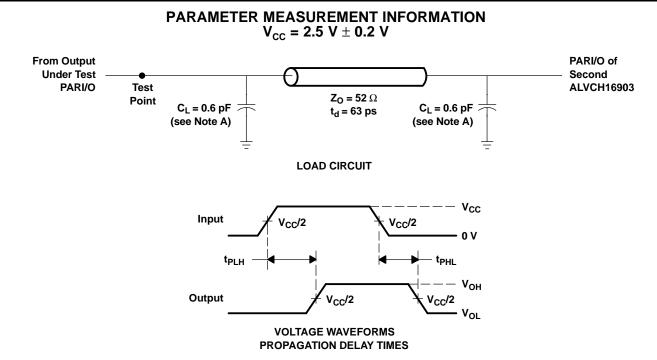
- NOTES: A. C<sub>1</sub> includes probe and jig capacitance.
  - B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
  - C. All input pulses are supplied by generators having the following characteristics: PRR  $\leq$  10 MHz, Z<sub>O</sub> = 50  $\Omega$ , t<sub>f</sub>  $\leq$  2 ns, t<sub>f</sub>  $\leq$  2 ns.
  - D. The outputs are measured one at a time, with one transition per measurement.
  - E. t<sub>PLZ</sub> and t<sub>PHZ</sub> are the same as t<sub>dis</sub>.
  - F.  $t_{PZL}$  and  $t_{PZH}$  are the same as  $t_{en}$ .
  - G.  $t_{PLH}$  and  $t_{PHL}$  are the same as  $t_{pd}$ .
  - H.  $t_{PHL}$  is measured at V<sub>CC</sub>/2.
  - I. t<sub>PLH</sub> is measured at V<sub>OL</sub> + 0.15 V.

Figure 1. Load Circuit and Voltage Waveforms



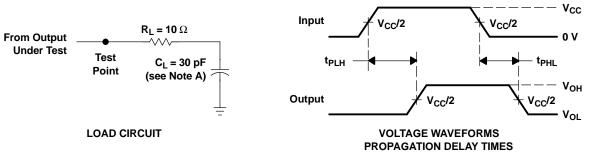
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- NOTES: A.  $C_L$  includes probe and jig capacitance.
  - B. All input pulses are supplied by generators having the following characteristics: PRR  $\leq$  10 MHz, Z<sub>0</sub> = 50  $\Omega$ , t<sub>f</sub>  $\leq$  2 ns, t<sub>f</sub>  $\leq$  2 ns.
  - C.  $t_{PLH}$  and  $t_{PHL}$  are the same as  $t_{pd}$ .

#### Figure 2. Load Circuit and Voltage Waveforms

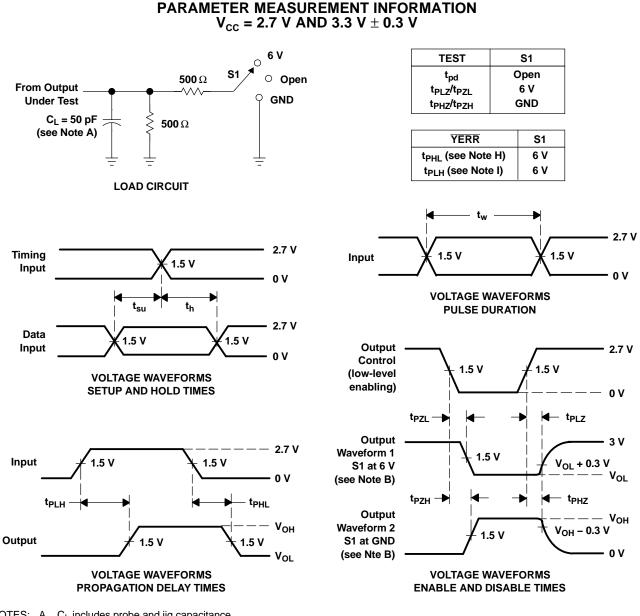


- NOTES: A.  $C_L$  includes probe and jig capacitance.
  - B. All input pulses are supplied by generators having the following characteristics: PRR  $\leq$  10 MHz, Z<sub>O</sub> = 50  $\Omega$ , t<sub>f</sub>  $\leq$  2 ns, t<sub>f</sub>  $\leq$  2 ns.

#### Figure 3. Load Circuit and Voltage Waveforms



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NOTES: A. C<sub>L</sub> includes probe and jig capacitance.

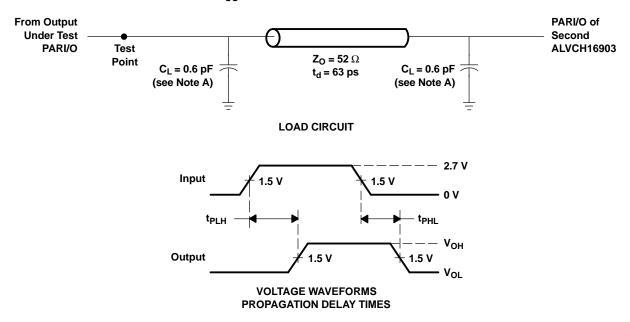
- B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control. C. All input pulses are supplied by generators having the following characteristics: PRR  $\leq$  10 MHz, Z<sub>Q</sub> = 50  $\Omega$ , t<sub>r</sub>  $\leq$  2.5 ns, t<sub>f</sub>  $\leq$  2.5 ns.
- D. The outputs are measured one at a time, with one transition per measurement.
- E.  $t_{PLZ}$  and  $t_{PHZ}$  are the same as  $t_{dis}$ .
- F. t<sub>PZL</sub> and t<sub>PZH</sub> are the same as t<sub>en</sub>.
- G.  $t_{PLH}$  and  $t_{PHL}$  are the same as  $t_{pd}$ .
- H. t<sub>PHL</sub> is measured at 1.5 V.
- I. t<sub>PLH</sub> is measured at V<sub>OL</sub> + 0.3 V.

#### Figure 4. Load Circuit and Voltage Waveforms



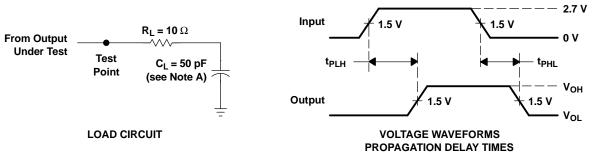
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# PARAMETER MEASUREMENT INFORMATION $V_{cc}$ = 2.7 V AND 3.3 V $\pm$ 0.3 V



- NOTES: A. C<sub>L</sub> includes probe and jig capacitance.
  - B. All input pulses are supplied by generators having the following characteristics: PRR  $\leq$  10 MHz, Z<sub>Q</sub> = 50  $\Omega$ , t<sub>r</sub>  $\leq$  2.5 ns, t<sub>f</sub>  $\leq$  2.5 ns.
  - C.  $t_{PLH}$  and  $t_{PHL}$  are the same as  $t_{pd}$ .

#### Figure 5. Load Circuit and Voltage Waveforms



- NOTES: A.  $C_L$  includes probe and jig capacitance.
  - B. All input pulses are supplied by generators having the following characteristics: PRR  $\leq$  10 MHz, Z<sub>O</sub> = 50  $\Omega$ , t<sub>r</sub>  $\leq$  2.5 ns, t<sub>f</sub>  $\leq$  2.5 ns.

#### Figure 6. Load Circuit and Voltage Waveforms

### PACKAGING INFORMATION

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins	Package Qty	e Eco Plan <sup>(2)</sup>	Lead/Ball Finish	MSL Peak Temp <sup>(3)</sup>
74ALVCH16903DGGRE4	ACTIVE	TSSOP	DGG	56	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
74ALVCH16903DGGRG4	ACTIVE	TSSOP	DGG	56	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
74ALVCH16903DGVRE4	ACTIVE	TVSOP	DGV	56	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
74ALVCH16903DGVRG4	ACTIVE	TVSOP	DGV	56	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
74ALVCH16903DLG4	ACTIVE	SSOP	DL	56	20	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
74ALVCH16903DLRG4	ACTIVE	SSOP	DL	56	1000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALVCH16903DGGR	ACTIVE	TSSOP	DGG	56	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALVCH16903DGVR	ACTIVE	TVSOP	DGV	56	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALVCH16903DL	ACTIVE	SSOP	DL	56	20	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALVCH16903DLR	ACTIVE	SSOP	DL	56	1000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

<sup>(1)</sup> The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

<sup>(2)</sup> Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

**Pb-Free (RoHS):** TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

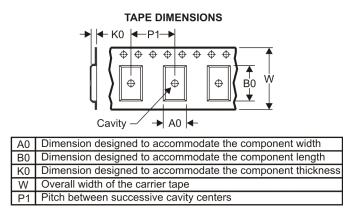
<sup>(3)</sup> MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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### TAPE AND REEL INFORMATION





# QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE

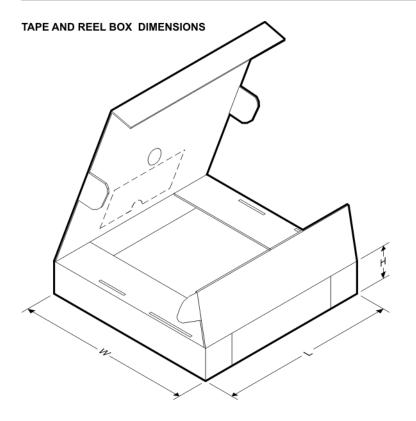


*All dimensions are nominal												
Device		Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74ALVCH16903DGGR	TSSOP	DGG	56	2000	330.0	24.4	8.6	15.6	1.8	12.0	24.0	Q1
SN74ALVCH16903DGVR	TVSOP	DGV	56	2000	330.0	24.4	6.8	11.7	1.6	12.0	24.0	Q1
SN74ALVCH16903DLR	SSOP	DL	56	1000	330.0	32.4	11.35	18.67	3.1	16.0	32.0	Q1



# PACKAGE MATERIALS INFORMATION

11-Mar-2008



\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74ALVCH16903DGGR	TSSOP	DGG	56	2000	346.0	346.0	41.0
SN74ALVCH16903DGVR	TVSOP	DGV	56	2000	346.0	346.0	41.0
SN74ALVCH16903DLR	SSOP	DL	56	1000	346.0	346.0	49.0

# **MECHANICAL DATA**

MSSO001C - JANUARY 1995 - REVISED DECEMBER 2001

#### PLASTIC SMALL-OUTLINE PACKAGE

48 PINS SHOWN

DL (R-PDSO-G\*\*)



NOTES: A. All linear dimensions are in inches (millimeters).

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).

D. Falls within JEDEC MO-118



# **MECHANICAL DATA**

MTSS003D - JANUARY 1995 - REVISED JANUARY 1998

### DGG (R-PDSO-G\*\*)

### PLASTIC SMALL-OUTLINE PACKAGE

**48 PINS SHOWN** 



NOTES: A. All linear dimensions are in millimeters.

- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold protrusion not to exceed 0,15.
- D. Falls within JEDEC MO-153



# **MECHANICAL DATA**

PLASTIC SMALL-OUTLINE

MPDS006C - FEBRUARY 1996 - REVISED AUGUST 2000

### DGV (R-PDSO-G\*\*)

24 PINS SHOWN



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15 per side.
- D. Falls within JEDEC: 24/48 Pins MO-153

14/16/20/56 Pins – MO-194



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